

MC14042B

Quad Transparent Latch

The MC14042B Quad Transparent Latch is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Each latch has a separate data input, but all four latches share a common clock. The clock polarity (high or low) used to strobe data through the latches can be reversed using the polarity input. Information present at the data input is transferred to outputs Q and \bar{Q} during the clock level which is determined by the polarity input. When the polarity input is in the logic "0" state, data is transferred during the low clock level, and when the polarity input is in the logic "1" state the transfer occurs during the high clock level.

- Buffered Data Inputs
- Common Clock
- Clock Polarity Control
- Q and \bar{Q} Outputs
- Double Diode Input Protection
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 2.)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V_{in}, V_{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I_{in}, I_{out}	Input or Output Current (DC or Transient) per Pin	± 10	mA
P_D	Power Dissipation, per Package (Note 3.)	500	mW
T_A	Ambient Temperature Range	-55 to +125	°C
T_{stg}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature (8-Second Soldering)	260	°C

2. Maximum Ratings are those values beyond which damage to the device may occur.

3. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

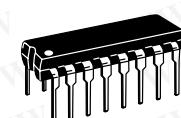
This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

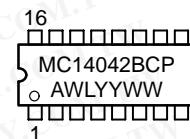


ON Semiconductor

MARKING DIAGRAMS



PDIP-16
P SUFFIX
CASE 648



MC14042BCP
AWLYYWW



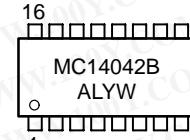
SOIC-16
D SUFFIX
CASE 751B



14042B
AWLYWW



SOEIAJ-16
F SUFFIX
CASE 966



MC14042B
ALYW

A = Assembly Location
 WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC14042BCP	PDIP-16	2000/Box
MC14042BD	SOIC-16	2400/Box
MC14042BDR2	SOIC-16	2500/Tape & Reel
MC14042BF	SOEIAJ-16	See Note 1.
MC14042BFEL	SOEIAJ-16	See Note 1.
MC14042BFR1	SOEIAJ-16	See Note 1.
MC14042BFR2	SOEIAJ-16	See Note 1.

- For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

MC14042B

PIN ASSIGNMENT

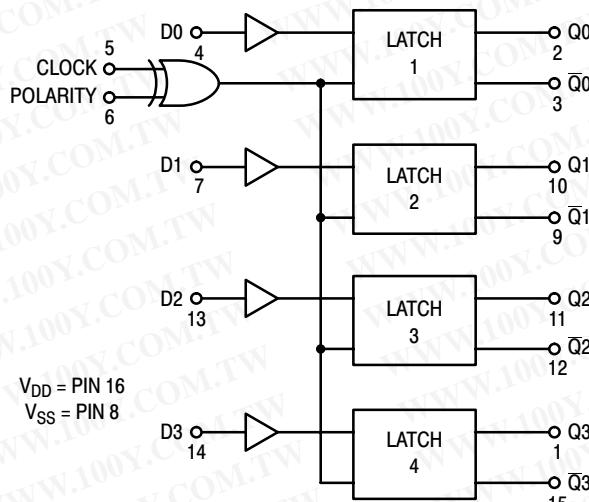
Q3	1 •	16	V _{DD}
Q0	2	15	Q̄3
Q̄0	3	14	D3
D0	4	13	D2
CLOCK	5	12	Q̄2
POLARITY	6	11	Q2
D1	7	10	Q1
V _{SS}	8	9	Q̄1

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TRUTH TABLE

Clock	Polarity	Q
0	0	Data
1	0	Latch
1	1	Data
0	1	Latch

LOGIC DIAGRAM



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V _{DD} Vdc	-55°C		25°C			125°C		Unit
			Min	Max	Min	Typ ^(4.)	Max	Min	Max	
Output Voltage V _{in} = V _{DD} or 0	V _{OL}	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
	V _{OH}	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	V _{IL}	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc
		10	—	3.0	—	4.50	3.0	—	3.0	
		15	—	4.0	—	6.75	4.0	—	4.0	
	V _{IH}	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
		10	7.0	—	7.0	5.50	—	7.0	—	
		15	11	—	11	8.25	—	11	—	
Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)	Source	I _{OH}	5.0	-3.0	—	-2.4	-4.2	—	-1.7	mAdc
			5.0	-0.64	—	-0.51	-0.88	—	-0.36	
			10	-1.6	—	-1.3	-2.25	—	-0.9	
			15	-4.2	—	-3.4	-8.8	—	-2.4	
	Sink	I _{OL}	5.0	0.64	—	0.51	0.88	—	0.36	mAdc
			10	1.6	—	1.3	2.25	—	0.9	
			15	4.2	—	3.4	8.8	—	2.4	
Input Current	I _{in}	15	—	±0.1	—	±0.00001	±0.1	—	±1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (Per Package)	I _{DD}	5.0	—	1.0	—	0.002	1.0	—	30	μAdc
Total Supply Current ^(5.) ^(6.) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs all buffers switching)	I _T	5.0	I _T = (1.0 μA/kHz) f + I _{DD} I _T = (2.0 μA/kHz) f + I _{DD} I _T = (3.0 μA/kHz) f + I _{DD}						60	μAdc
		10							120	

4. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

5. The formulas given are for the typical characteristics only at 25°C.

6. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} - V_{SS}) in volts, f in kHz is input frequency, and k = 0.004.

SWITCHING CHARACTERISTICS (7.) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	V_{DD}	Min	Typ (8.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t_{TLH}, t_{THL}	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Time, D to Q, \bar{Q} $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 135 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 57 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 35 \text{ ns}$	t_{PLH}, t_{PHL}	5.0 10 15	— — —	220 90 60	440 180 120	ns
Propagation Delay Time, Clock to Q, \bar{Q} $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 135 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 57 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 35 \text{ ns}$	t_{PLH}, t_{PHL}	5.0 10 15	— — —	220 90 60	440 180 120	ns
Clock Pulse Width	t_{WH}	5.0 10 15	300 100 80	150 50 40	— — —	ns
Clock Pulse Rise and Fall Time	t_{TLH}, t_{THL}	5.0 10 15	— — —	— — —	15 5.0 4.0	μs
Hold Time	t_h	5.0 10 15	100 50 40	50 25 20	— — —	ns
Setup Time	t_{su}	5.0 10 15	50 30 25	0 0 0	— — —	ns

7. The formulas given are for the typical characteristics only at 25°C .

8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

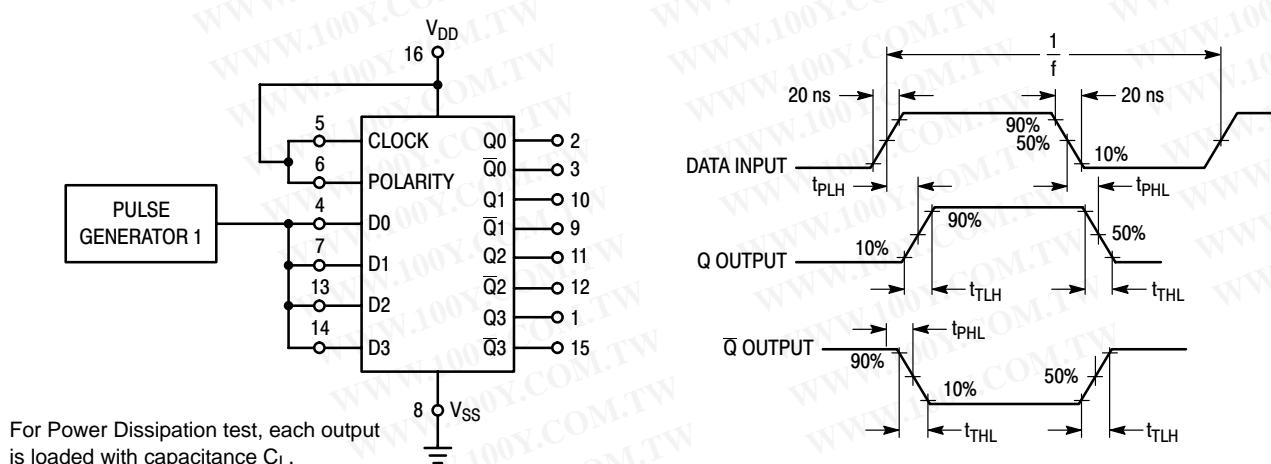
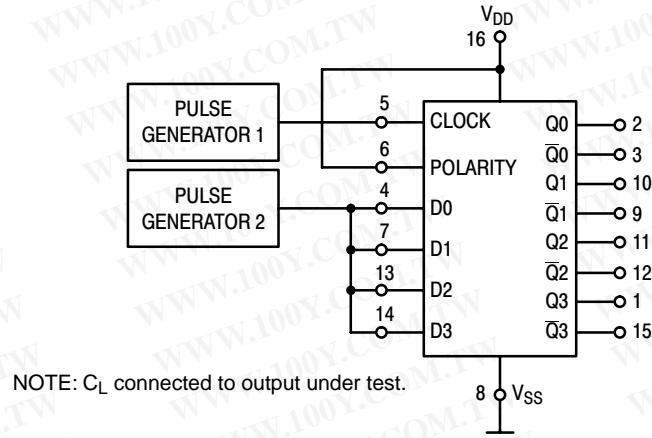
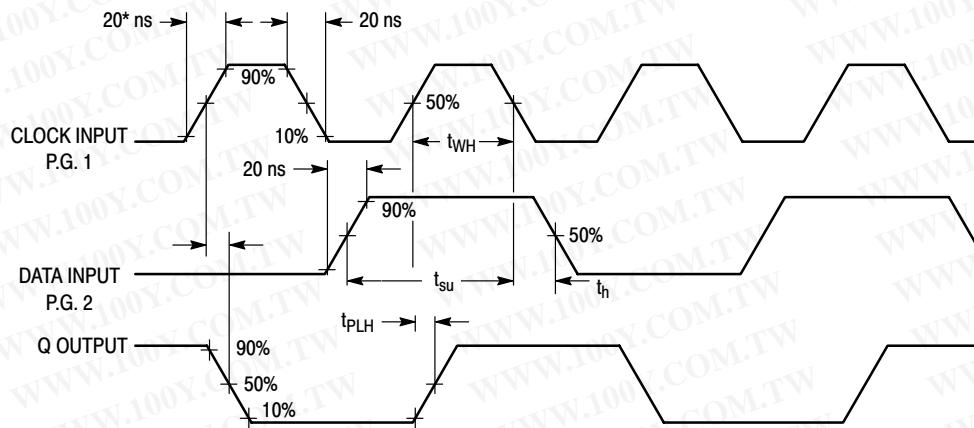


Figure 1. AC and Power Dissipation Test Circuit and Timing Diagram
(Data to Output)

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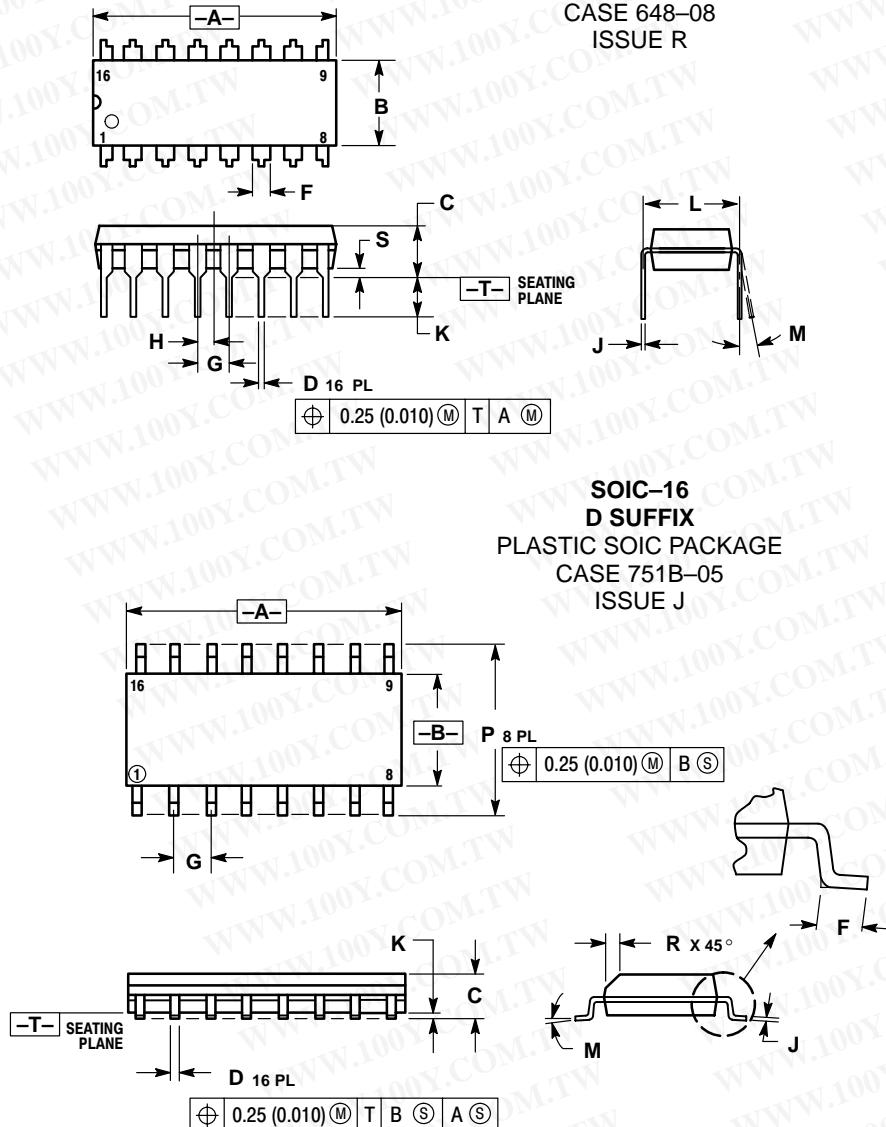


*Input clock rise time is 20 ns except for maximum rise time test.

**Figure 2. AC Test Circuit and Timing Diagram
(Clock to Output)**

MC14042B

PACKAGE DIMENSIONS



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 胜特力电子(深圳) 86-755-83298787
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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

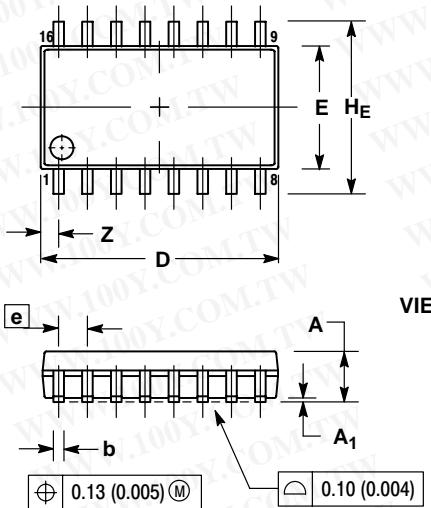
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

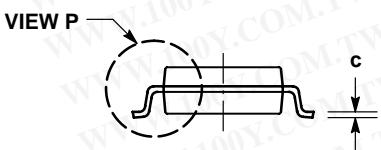
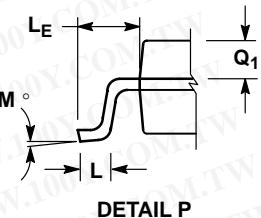
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

MC14042B

PACKAGE DIMENSIONS



**SOEIAJ-16
F SUFFIX**
PLASTIC EIAJ SOIC PACKAGE
CASE 966-01
ISSUE O



勝特力材料 886-3-5753170
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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031